ABSTRACT

A pattern inspection method in which an image can be detecte d without an image detection error due to an adverse effect to be given implan ted in factors as ions wafer, pattern and pattern edge formation. connection/no-connection, A digital image of an object substra te is attained through microscopic obser vation the attained digital image is examined to detect defects while masking a region pre-registered in terms of coordinates or while masking a pattern meeting a pre-registered pattern, and an image of each of the defects thus detected is displayed. Furthe r, each of the defects detected using the digital ,image attained through microscopic observation checked to judge whether its feature meets a pre-registered feature or Defects having a feature that meets the pre-registered feature are so displayed that they can be turned/o ff, or they are so displayed as to be distinguishable from the other defects.